Product Summary

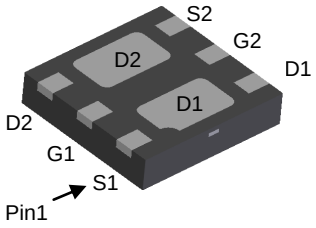
Device	BV_{DSS}	$R_{DS(ON)\ MAX}$	$I_{D\ MAX}$ T_A = +25°C
Q1 N-Channel	12V	34mΩ @ V_{GS} = 4.5V	5.1A
		40mΩ @ V_{GS} = 2.5V	4.7A
		50mΩ @ V_{GS} = 1.8V	4.2A
		70mΩ @ V_{GS} = 1.5V	3.6A
Q2 P-Channel	-12	59mΩ @ V_{GS} = -4.5V	-3.9A
		81mΩ @ V_{GS} = -2.5V	-3.3A
		115mΩ @ V_{GS} = -1.8V	-2.8A
		215mΩ @ V_{GS} = -1.5V	-2.0A

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Load Switch
- Power Management Functions
- Portable Power Adaptors

U-DFN2020-6 (Type B)



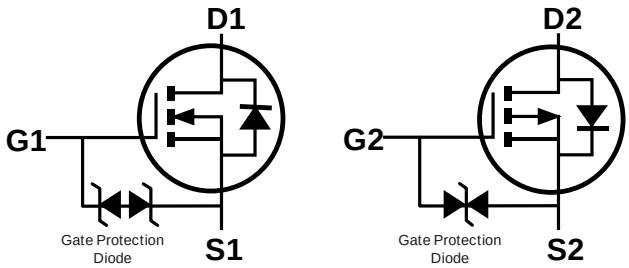
Bottom View

Features

- Low On-Resistance
- Low Input Capacitance
- Low Profile, 0.6mm Max Height
- **ESD Protected Gate**
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: U-DFN2020-6 (Type B)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 e4
- Terminals Connections: See Diagram Below
- Weight: 0.0065 grams (Approximate)



N-CHANNEL MOSFET P-CHANNEL MOSFET

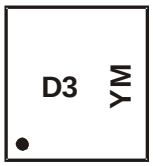
Internal Schematic

Ordering Information (Note 5)

Part Number	Case	Packaging
DMC1030UFDBQ-7	U-DFN2020-6 (Type B)	3000/Tape & Reel
DMC1030UFDBQ-13	U-DFN2020-6 (Type B)	10000/Tape & Reel

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.
5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



D3 = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: D = 2016)
M = Month (ex: 9 = September)

Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021
Code	C	D	E	F	G	H	I

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Q1 N-CHANNEL	Q2 P-CHANNEL	Unit
Drain-Source Voltage			V_{DSS}	12	-12	V
Gate-Source Voltage			V_{GSS}	±8	±8	V
Continuous Drain Current (Note 6) N-CHANNEL: V_{GS} = 4.5V P-CHANNEL: V_{GS} = -4.5V	Steady State	T_A = +25°C T_A = +70°C	I_D	5.1 4.1	-3.9 -3.1	A
	t < 5s	T_A = +25°C T_A = +70°C	I_D	6.6 5.3	-5.0 -4.0	A
Maximum Continuous Body Diode Forward Current (Note 6)			I_S	2	-1.7	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I_{DM}	35	-25	A
Avalanche Current (L = 0.1mH)			I_{AS}	5	-5	A
Avalanche Energy (L = 0.1mH)			E_{AS}	4	4	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	Steady State	P_D	1.36	W
	t < 5s		1.89	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	92	°C/W
	t < 5s		66	
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	18	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics Q1 N-CHANNEL (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	12	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current T_J = +25°C	I_{DSS}	—	—	1.0	µA	V_{DS} = 12V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±10	µA	V_{GS} = ±8V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	0.4	—	1	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	17	34	mΩ	V_{GS} = 4.5V, I_D = 4.6A
		—	20	40		V_{GS} = 2.5V, I_D = 4.2A
		—	24	50		V_{GS} = 1.8V, I_D = 3.8A
		—	28	70		V_{GS} = 1.5V, I_D = 1.5A
Diode Forward Voltage	V_{SD}	—	0.7	1.2	V	V_{GS} = 0V, I_S = 4.8A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	1003	—	pF	V_{DS} = 6V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	—	132	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	115	—	pF	
Gate Resistance	R_g	—	11.3	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = 4.5V)	Q_g	—	12.2	—	nC	V_{DS} = 10V, I_D = 6.8A
Total Gate Charge (V_{GS} = 8V)		—	23.1	—	nC	
Gate-Source Charge	Q_{gs}	—	1.3	—	nC	
Gate-Drain Charge	Q_{gd}	—	1.5	—	nC	
Turn-On Delay Time	$t_{D(ON)}$	—	4.4	—	ns	V_{DD} = 6V, V_{GS} = 4.5V, R_L = 1.1Ω, R_G = 1Ω
Turn-On Rise Time	t_R	—	7.4	—	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	18.8	—	ns	
Turn-Off Fall Time	t_F	—	4.9	—	ns	
Body Diode Reverse Recovery Time	t_{RR}	—	7.6	—	ns	I_S = 5.4A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q_{RR}	—	0.9	—	nC	I_S = 5.4A, dI/dt = 100A/µs

Notes: 6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

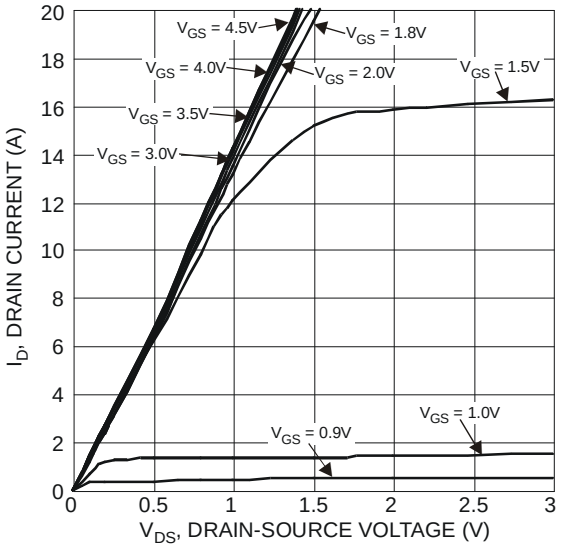


Figure 1 Typical Output Characteristics

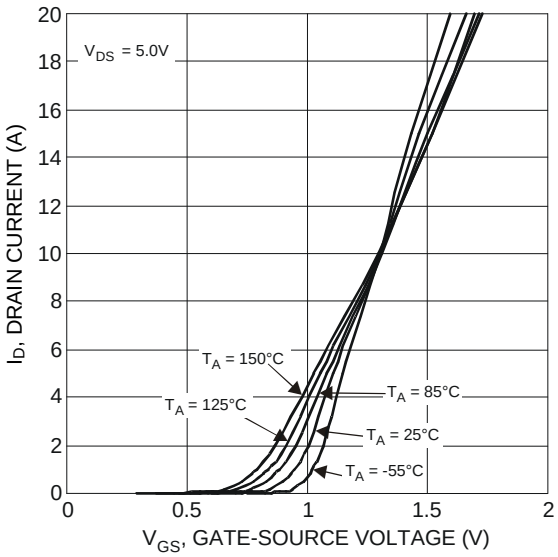


Figure 2 Typical Transfer Characteristics

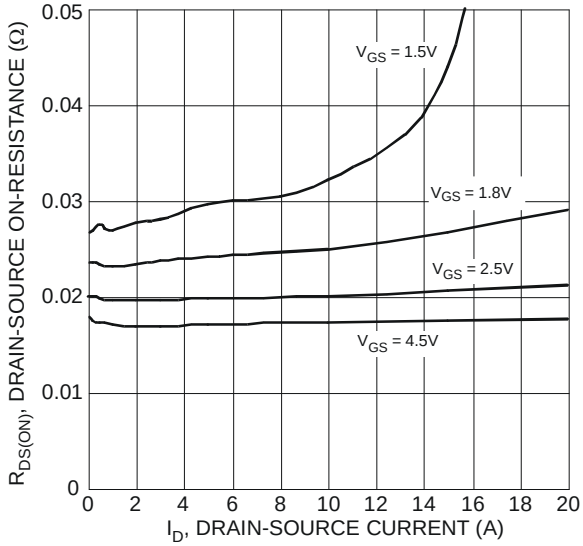


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

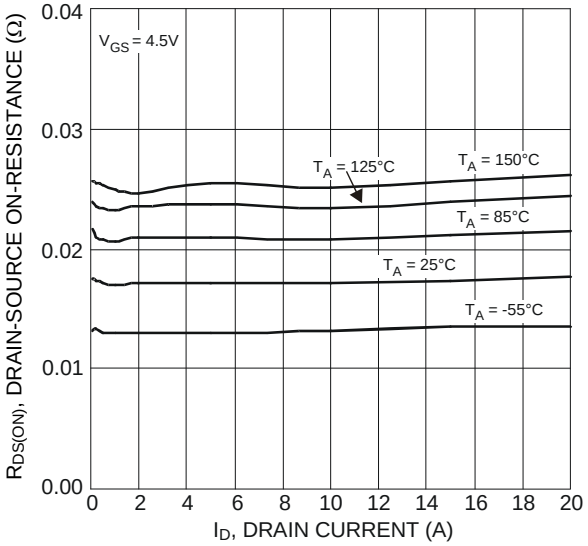


Figure 4 Typical On-Resistance vs. Drain Current and Temperature

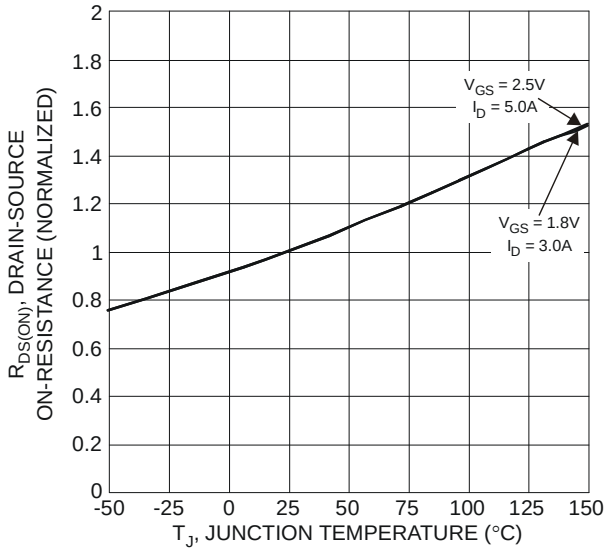


Figure 5 On-Resistance Variation with Temperature

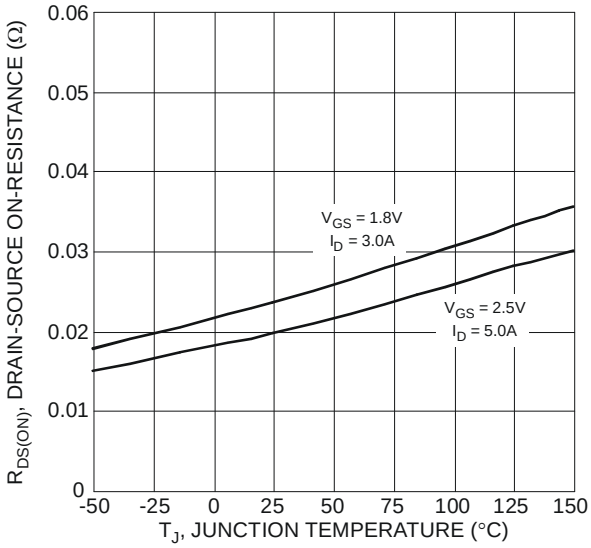


Figure 6 On-Resistance Variation with Temperature

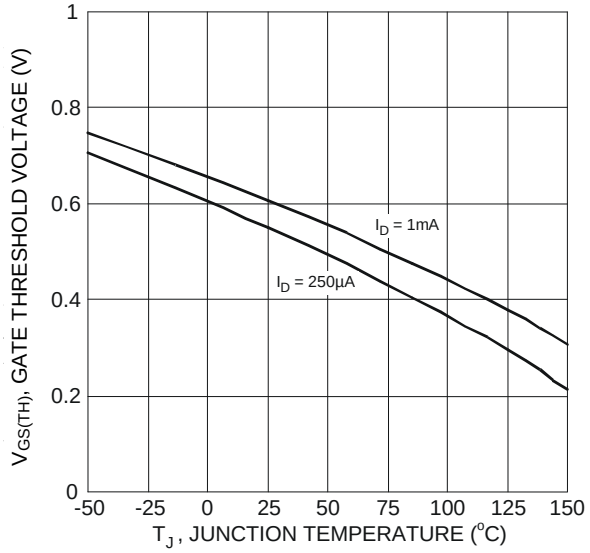


Figure 7 Gate Threshold Variation vs. Junction Temperature

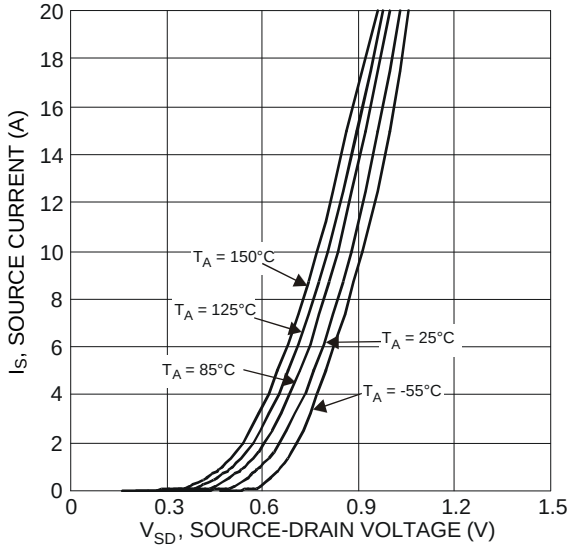


Figure 8 Diode Forward Voltage vs. Current

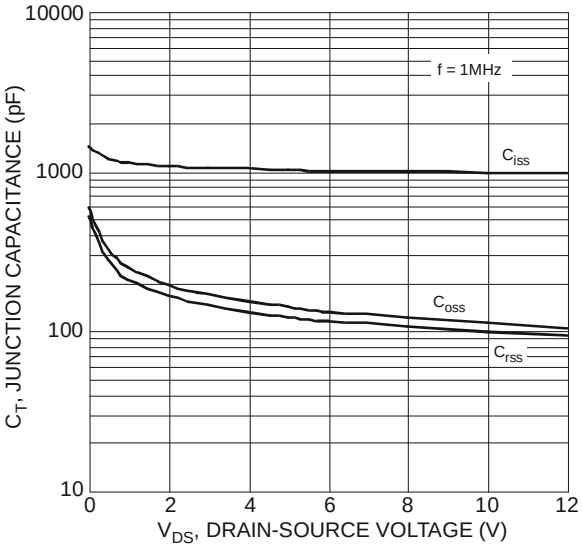


Figure 9 Typical Junction Capacitance

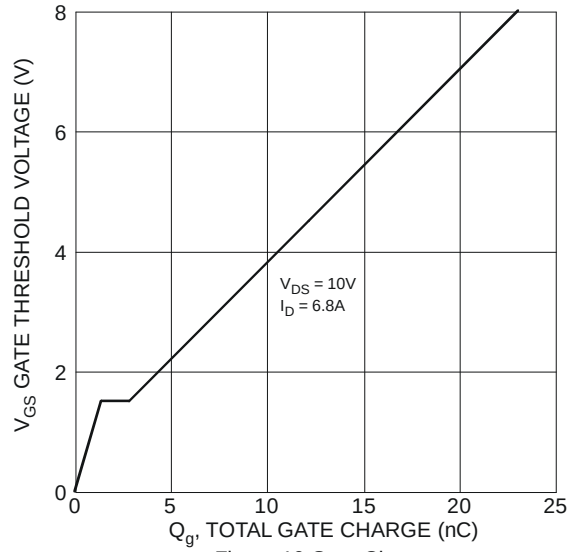


Figure 10 Gate Charge

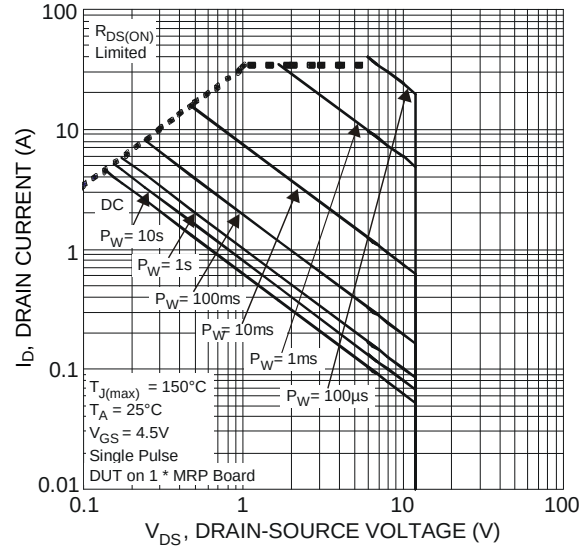


Figure 11 SOA Safe Operation Area

Electrical Characteristics Q2 P-CHANNEL (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	-12	—	—	V	V_{GS} = 0V, I_D = -250µA
Zero Gate Voltage Drain Current T_J = +25°C	I_{DSS}	—	—	-1.0	µA	V_{DS} = -12V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±10	µA	V_{GS} = ±8V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	-0.4	—	-1	V	V_{DS} = V_{GS}, I_D = -250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	37	59	mΩ	V_{GS} = -4.5V, I_D = -3.6A
		—	48	81		V_{GS} = -2.5V, I_D = -3.1A
		—	69	115		V_{GS} = -1.8V, I_D = -2.6A
		—	88	215		V_{GS} = -1.5V, I_D = -0.5A
Diode Forward Voltage	V_{SD}	—	-0.7	-1.2	V	V_{GS} = 0V, I_S = -3.7A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	1028	—	pF	V_{DS} = -6V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	—	285	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	254	—	pF	
Gate Resistance	R_g	—	19.6	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = -4.5V)	Q_g	—	13	—	nC	V_{DS} = -10V, I_D = -4.7A
Total Gate Charge (V_{GS} = -8V)		—	20.8	—	nC	
Gate-Source Charge	Q_{gs}	—	1.8	—	nC	
Gate-Drain Charge	Q_{gd}	—	4.5	—	nC	
Turn-On Delay Time	$t_{D(ON)}$	—	5.6	—	ns	V_{DD} = -6V, V_{GS} = -4.5V, R_L = 1.6Ω, R_G = 1Ω
Turn-On Rise Time	t_R	—	12.8	—	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	30.7	—	ns	
Turn-Off Fall Time	t_F	—	25.4	—	ns	
Body Diode Reverse Recovery Time	t_{RR}	—	31.6	—	ns	I_S = -3.6A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q_{RR}	—	7.8	—	nC	I_S = -3.6A, dI/dt = 100A/µs

Notes: 7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

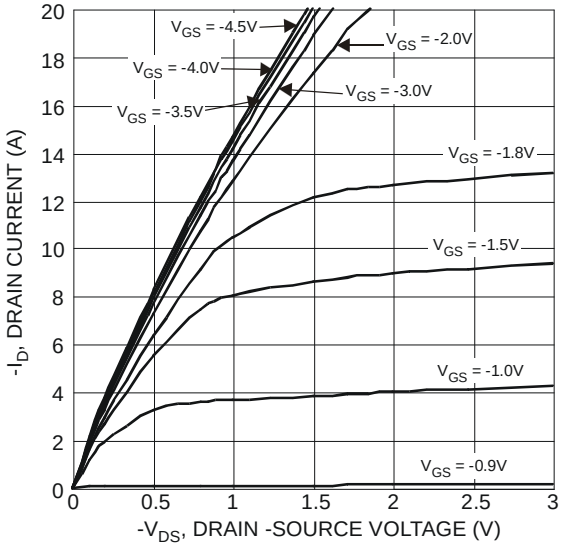


Figure 12 Typical Output Characteristics

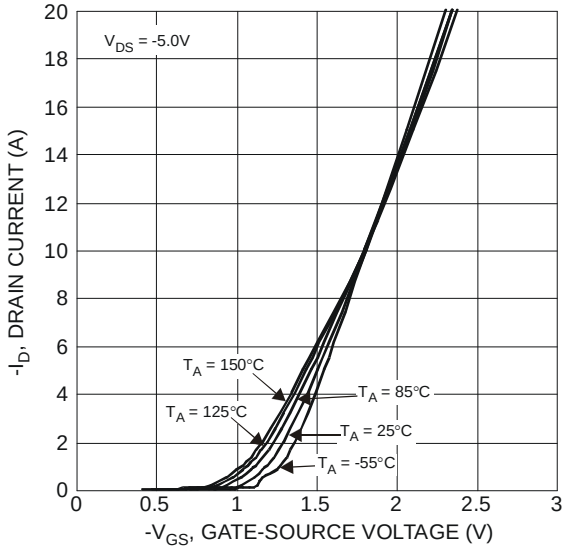


Figure 13 Typical Transfer Characteristics

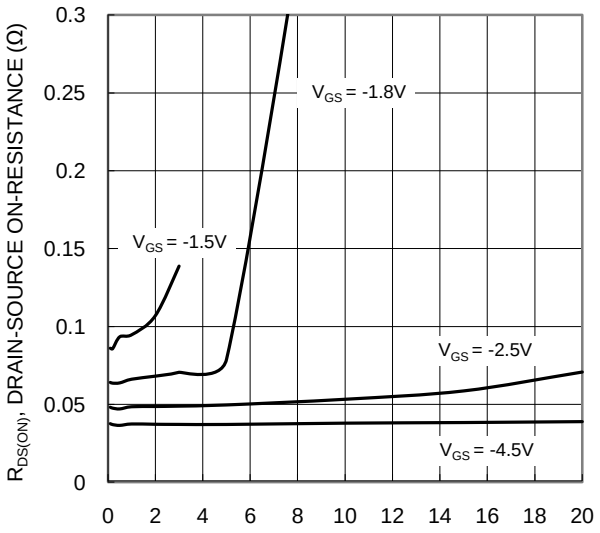


Figure 14 Typical On-Resistance vs. Drain Current and Gate Voltage

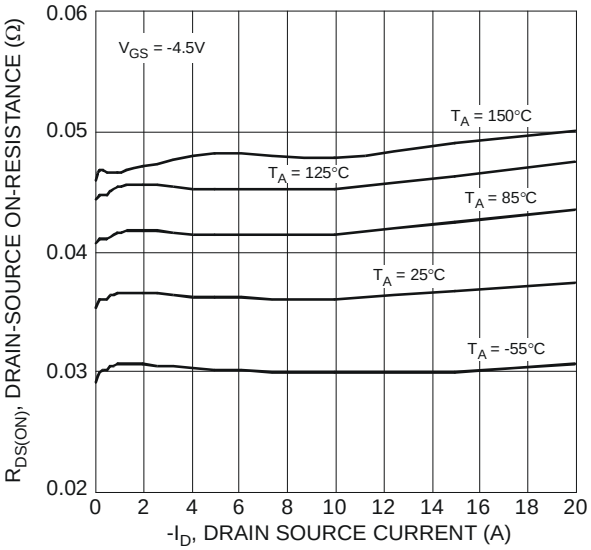


Figure 15 Typical On-Resistance vs. Drain Current and Temperature

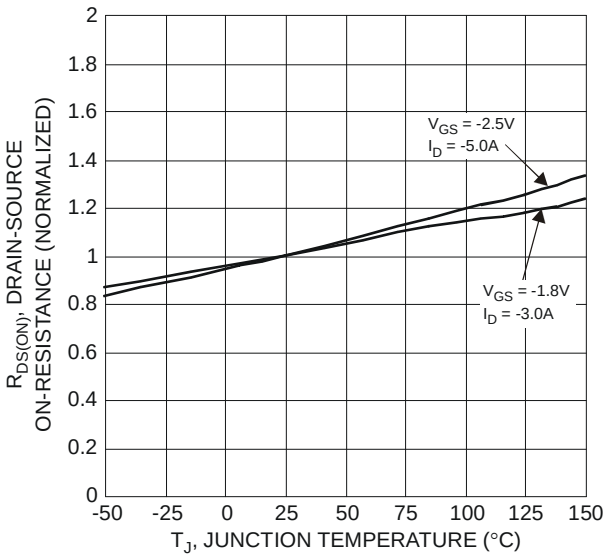


Figure 16 On-Resistance Variation with Temperature

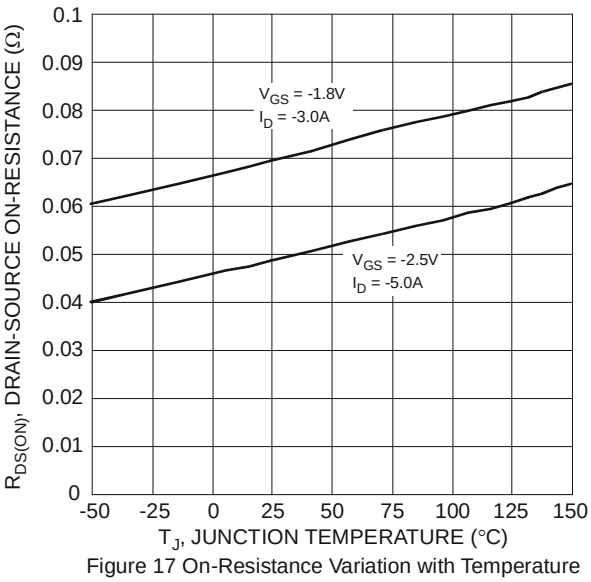


Figure 17 On-Resistance Variation with Temperature

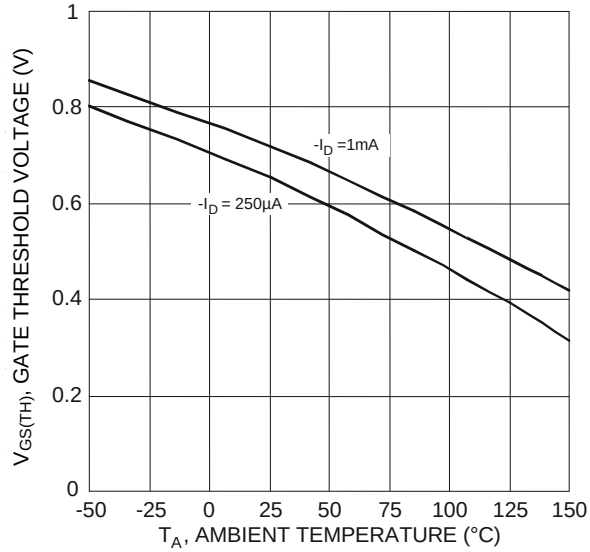


Figure 18 Gate Threshold Variation vs. Ambient Temperature

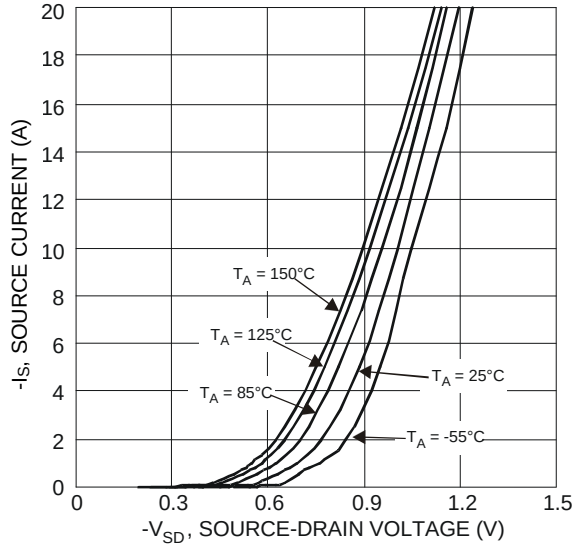


Figure 19 Diode Forward Voltage vs. Current

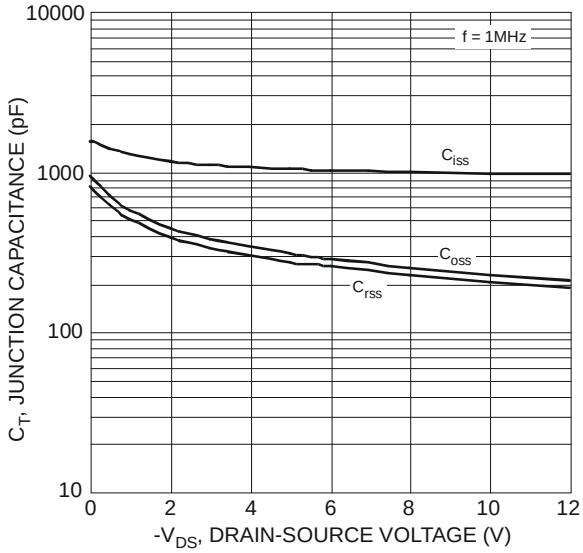


Figure 20 Typical Junction Capacitance

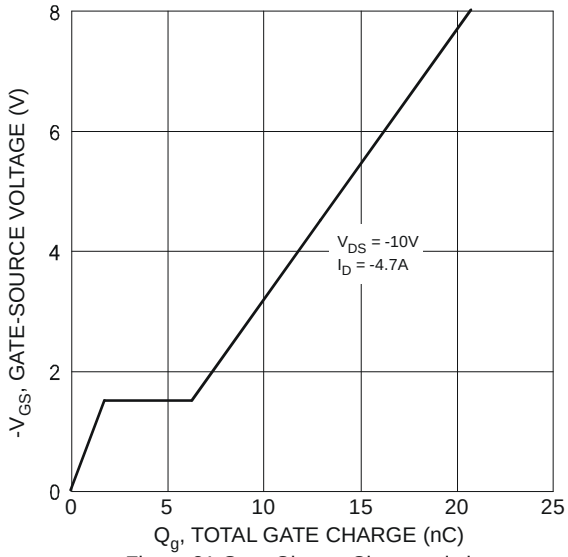


Figure 21 Gate-Charge Characteristics

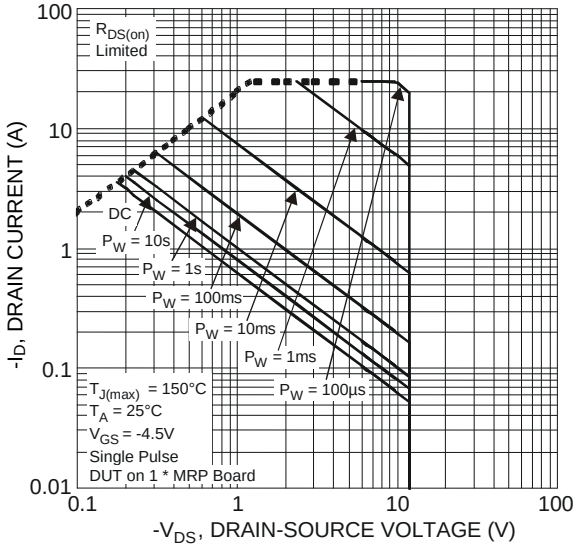


Figure 22 SOA Safe Operation Area

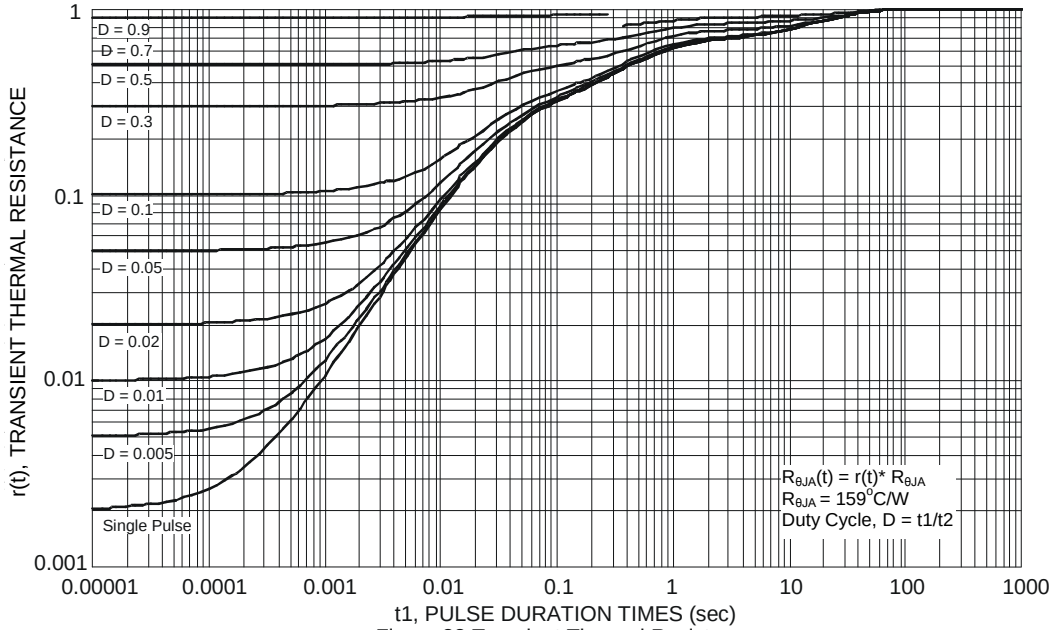
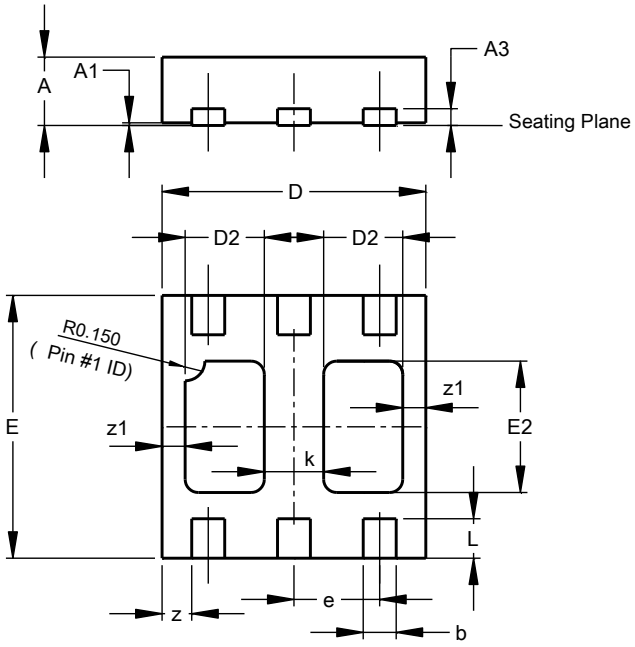


Figure 23 Transient Thermal Resistance

Package Outline Dimensions

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.

U-DFN2020-6 (Type B)

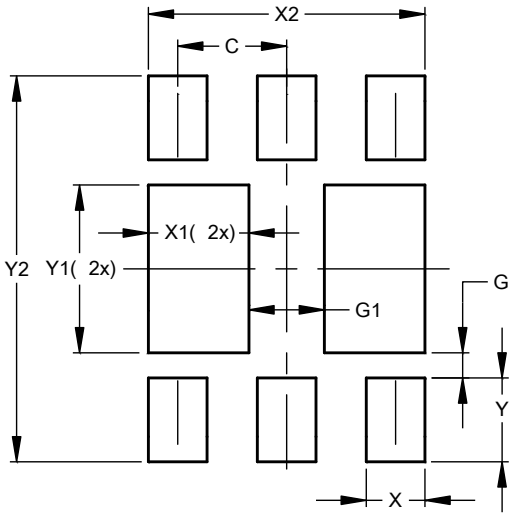


U-DFN2020-6 Type B			
Dim	**Min**	**Max**	**Typ**
A	0.545	0.605	0.575
A1	0.00	0.05	0.02
A3	-	-	0.13
b	0.20	0.30	0.25
D	1.95	2.075	2.00
D2	0.50	0.70	0.60
e	-	-	0.65
E	1.95	2.075	2.00
E2	0.90	1.10	1.00
k	-	-	0.45
L	0.25	0.35	0.30
z	-	-	0.225
z1	-	-	0.175
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.

U-DFN2020-6 (Type B)



Dimensions	Value (in mm)
C	0.650
G	0.150
G1	0.450
X	0.350
X1	0.600
X2	1.650
Y	0.500
Y1	1.000
Y2	2.300

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LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

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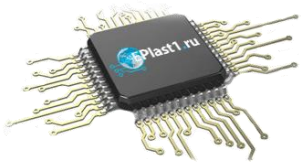
Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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